

ARTIST2 Summer School 2008 in Europe

Autrans (near Grenoble), France

September 8-12, 2008

Heterogeneous Platforms for Embedded Systems

Invited Speaker: Giovanni De Micheli

EPFL

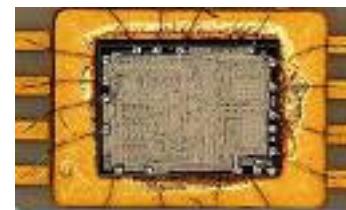


Quo vadis ?

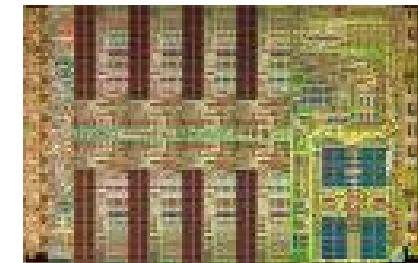
- We came a long way ...
 - 50 years of electronics



[Bell labs]

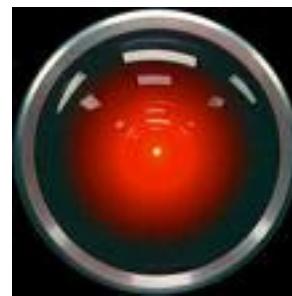


[Intel]



[IBM]

- ... and where are we going?
 - The next 50 years



[Kubrick:2001]

How did we affect society ?

- From transistor radio ...



[Motorola]



[IBM]



[Sony]

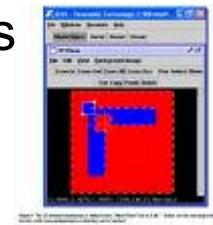
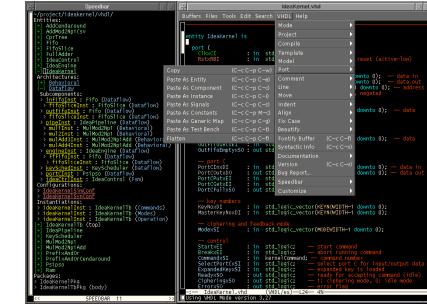


[Apple]

- Entertainment, personal computing, communication
- Can we have a deeper impact into market and society?
 - Who will benefit?
 - Socially?
 - Economically? Which market sector?

How did we engineer products ?

- Electronic Design Automation (EDA)
 - Provides us with the enabling technology
 - Formal modeling, analysis, synthesis
- But EDA
 - ... is entangled in solving *deep submicron* issues
 - ... missed opportunities at system-level design
 - ... is still a small niche market
- Can we reposition DA as a central engineering task?
 - Broader in scope
 - Scientifically challenging
 - Attracting the best young researchers
 - Creating more value



The next fifty years...

- Ubiquitously-distributed electronics
 - Electronic circuits and systems distributed in clothing, car, home, office, environment...
- A global market affecting everybody's everyday's life
- Some audacious goals:
 - Break language barriers
 - Eliminate energy dependence
 - Link up every human
 - Better health, safety and longevity
 - Protect and monitor our environment

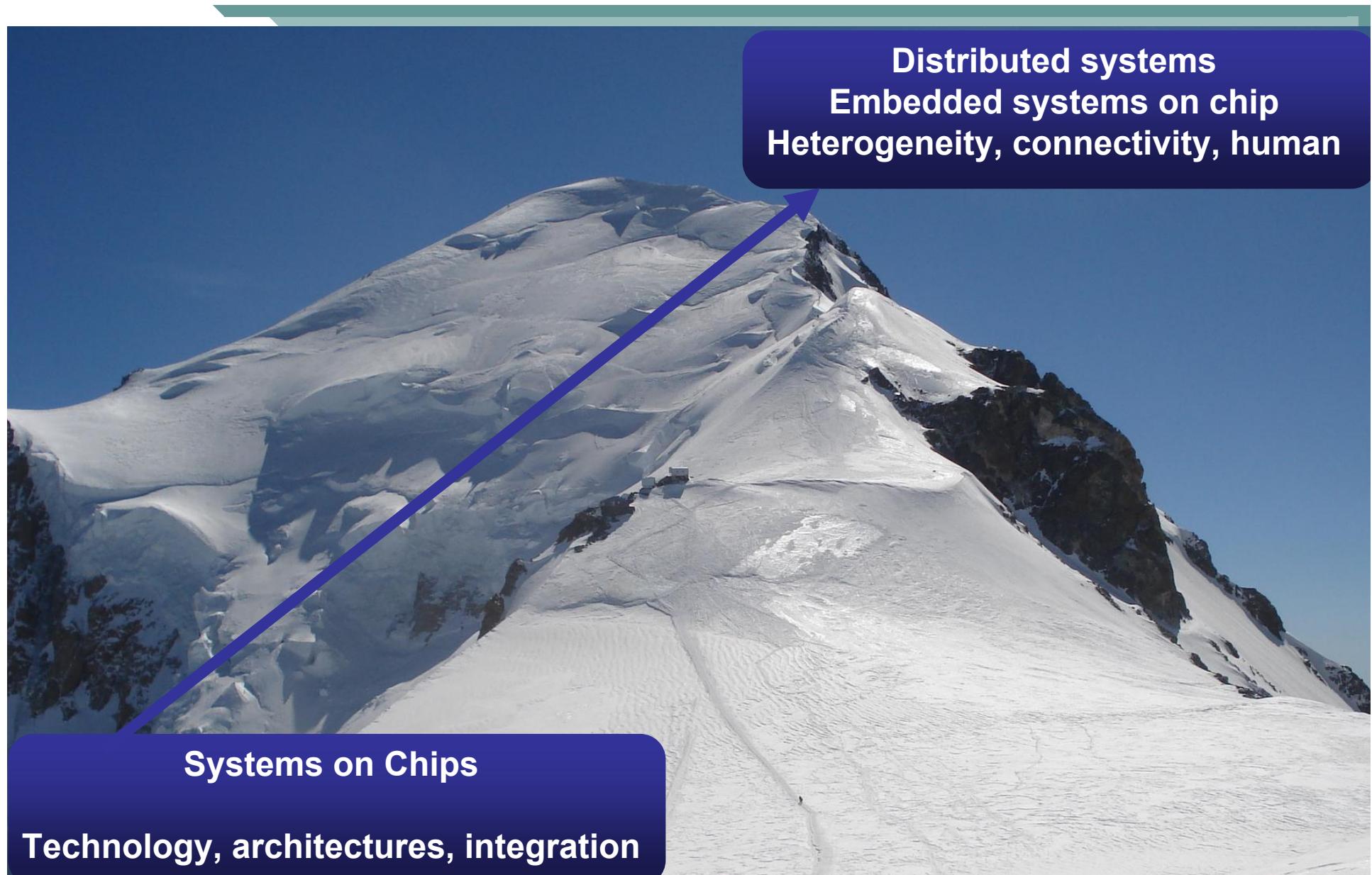


[Infineon]

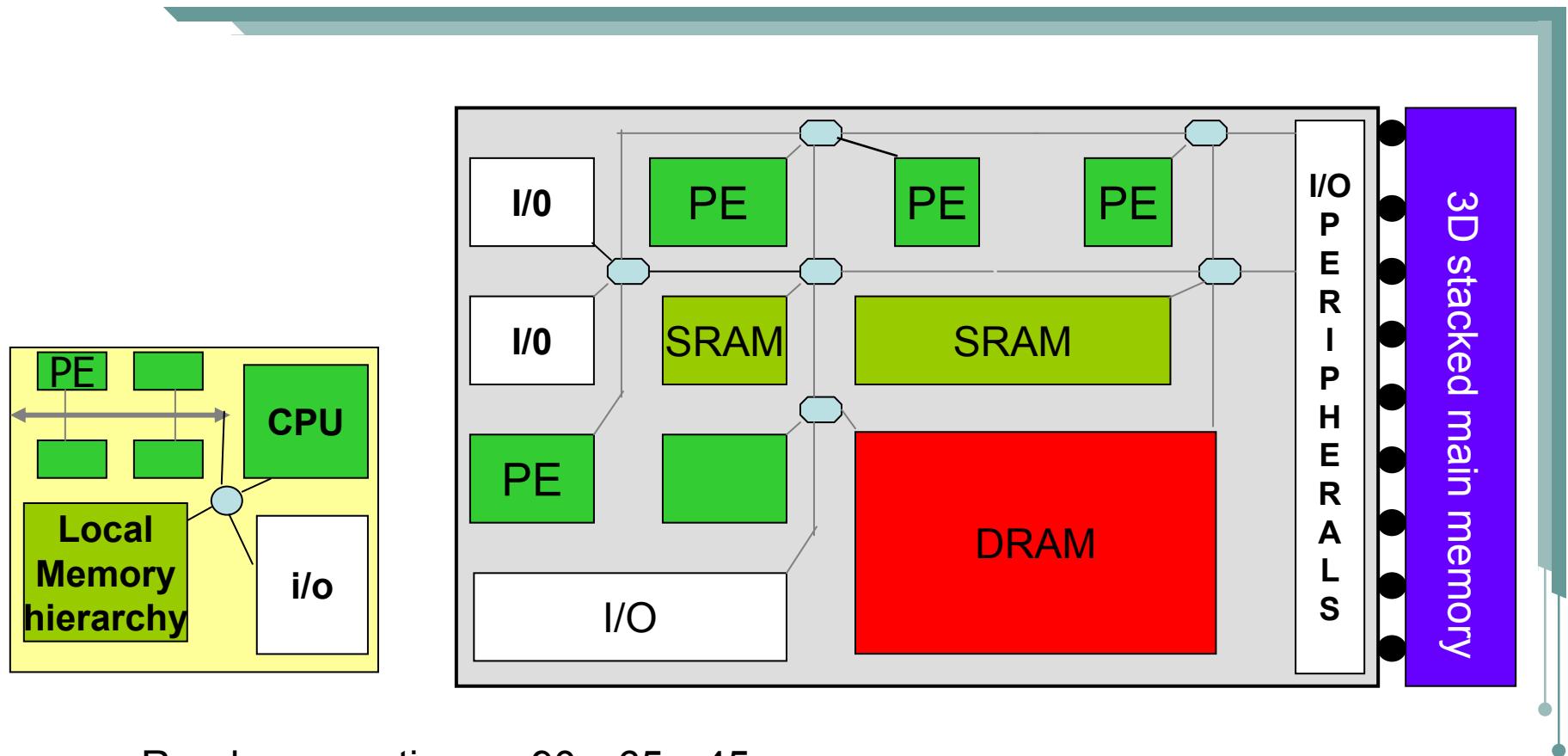


[QBUS Domotica]

The way ahead

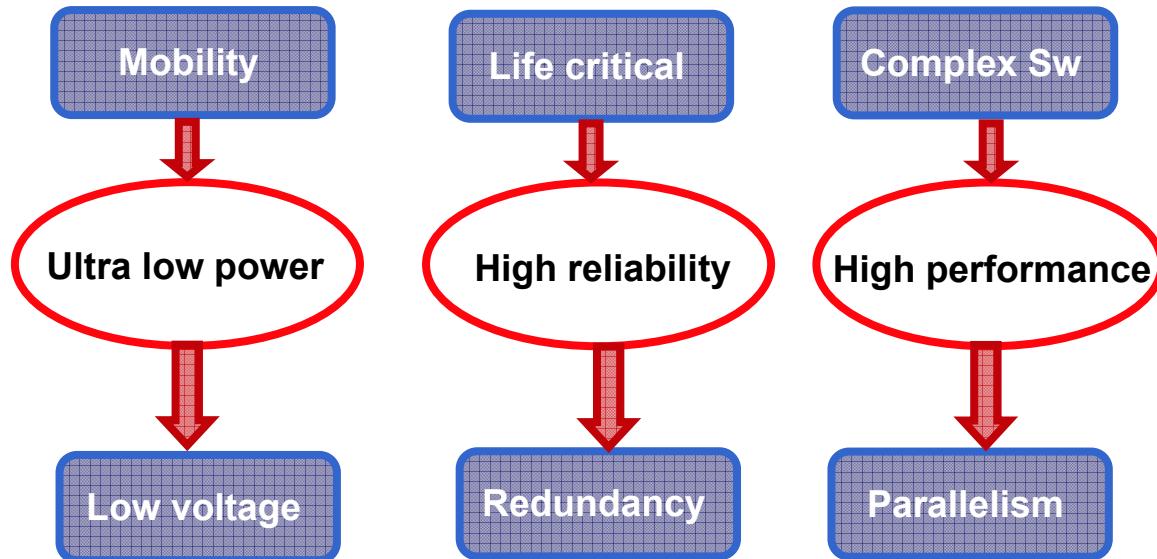


System on Chip evolution

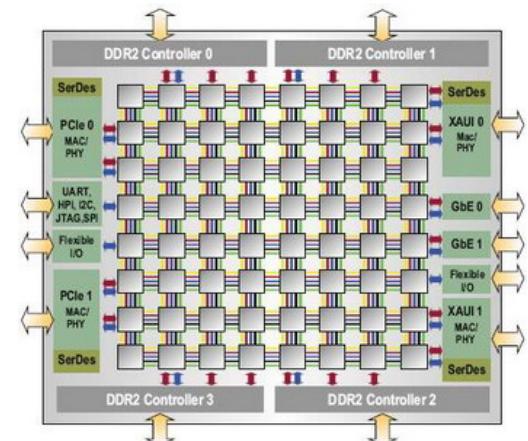


- Roadmap continues: $90 \rightarrow 65 \rightarrow 45$ nm
- “Traditional” Bus-based SoCs fit in one tile !!
- Communication demand is staggering, but unevenly distributed, because of architectural heterogeneity

Requirements for electronic chip design



- From processors to multi-processors
 - Technology support
 - Systems and software redesign



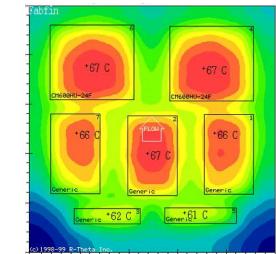
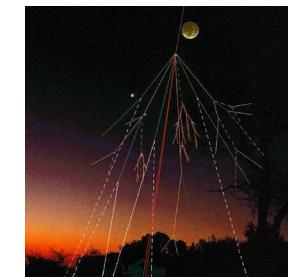
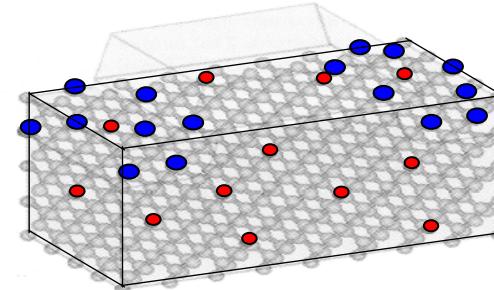
(c) Giovanni De Micheli -- Autrans 2008

Major SoC design issues

- **Variability**
 - Physical parameter variation
 - Microscopic structural effects

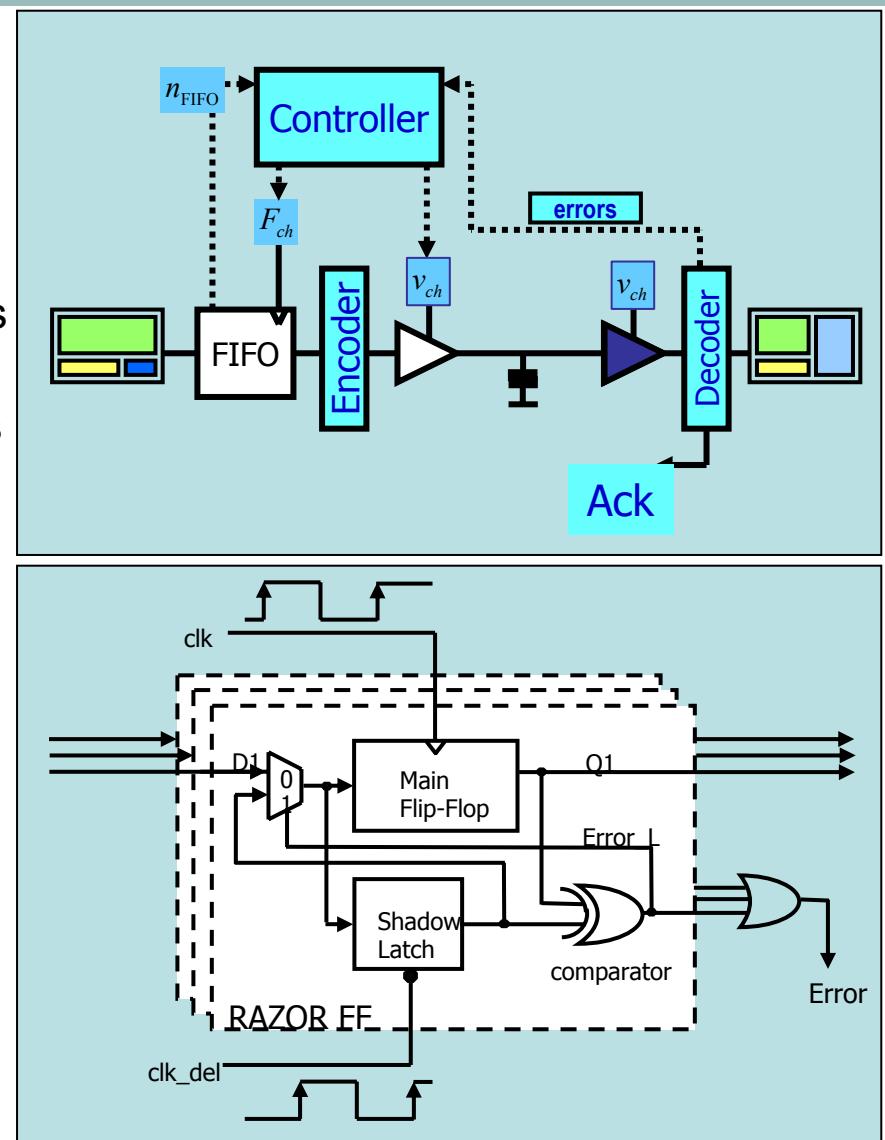
- **Reliability**
 - Higher failure rate
 - Higher exposure to environmental effects

- **Thermal management**
 - Heat extraction and temperature gradient avoidance
 - Temperature correlates with higher failure rates



Self-calibrating circuits

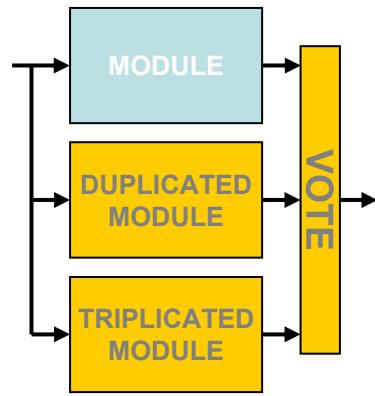
- Design self-calibrating circuits operating at the edge of failure
- Examples:
 - Dynamic voltage scaling of bus swings [Worm, lenne –EPFL]
 - Dynamic voltage scaling in processors
 - Razor [Austin – U Michigan]
 - Dynamic latency adjustment for NoCs
 - Terror [Tmhankar -Stanford]
- Autonomic computing
 - Systems that understand and react to environment [IBM]



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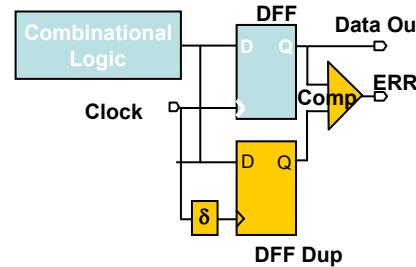
Soft-error protection

Redundancy (TMR)



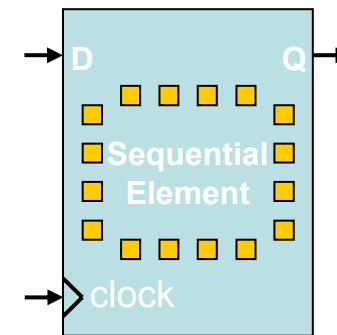
100% to 200% overhead

Detection + System Correction



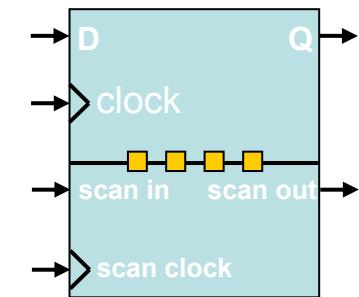
ERR signal used by system
(Hardware or Software) to correct the error

Hardened Libraries



■ Protection
Transistor
embedded in
the cell

Other Techniques



Scan Sequential Element

SCAN hardware used as
DETECTION hardware in
functional mode

Redundancy

Shielding

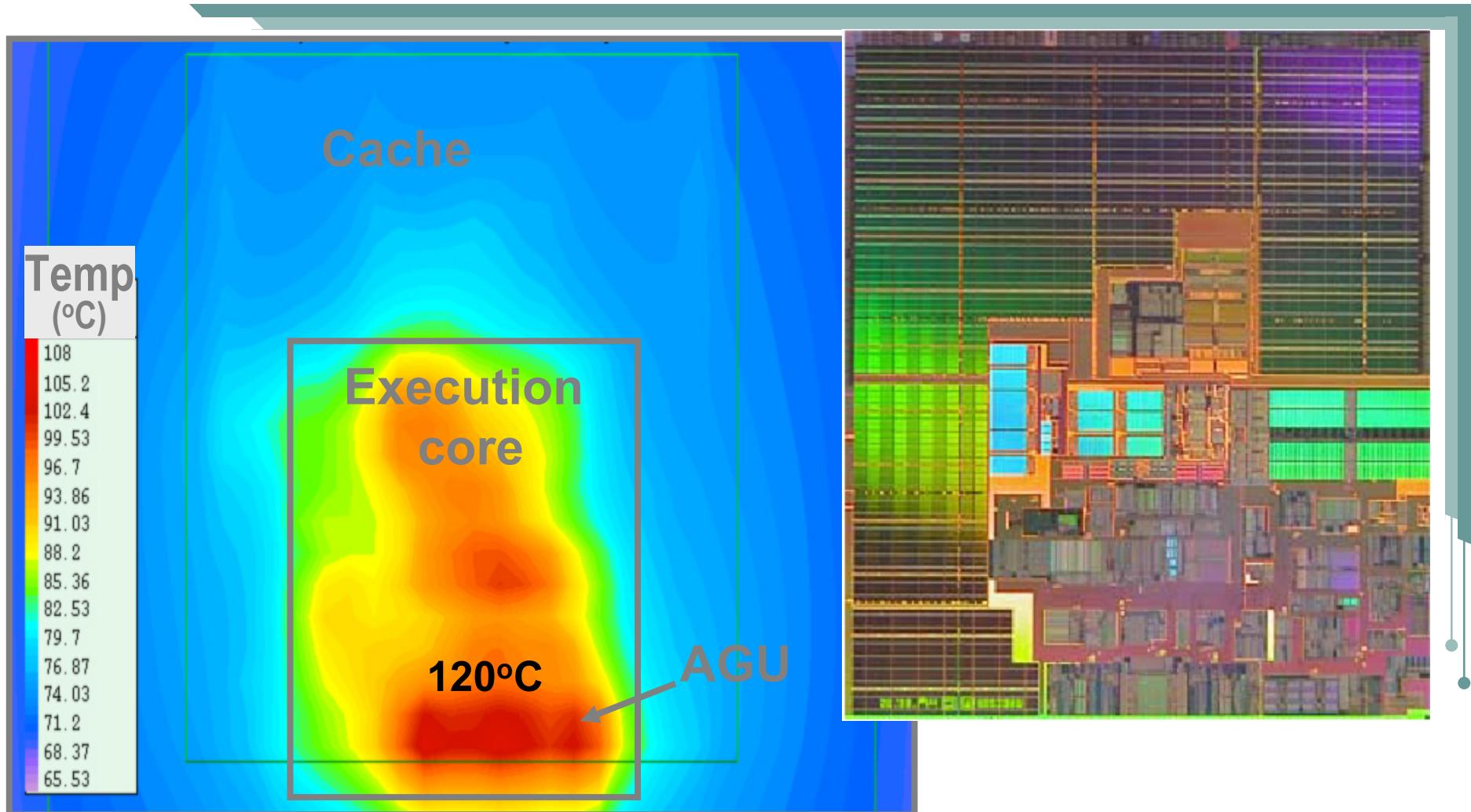
Others

[Source IROC]

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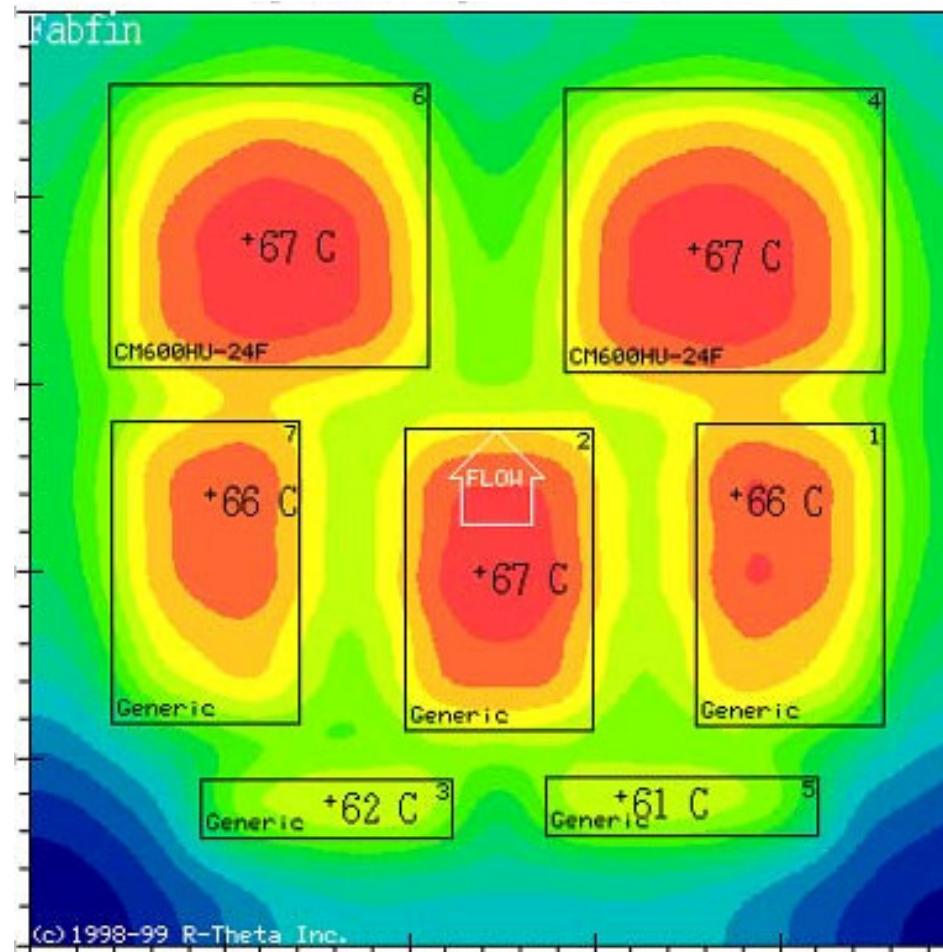
Thermal issues

1.5 GHz Itanium-2



[Source: Intel Corporation and Prof. V. Oklobdzija]

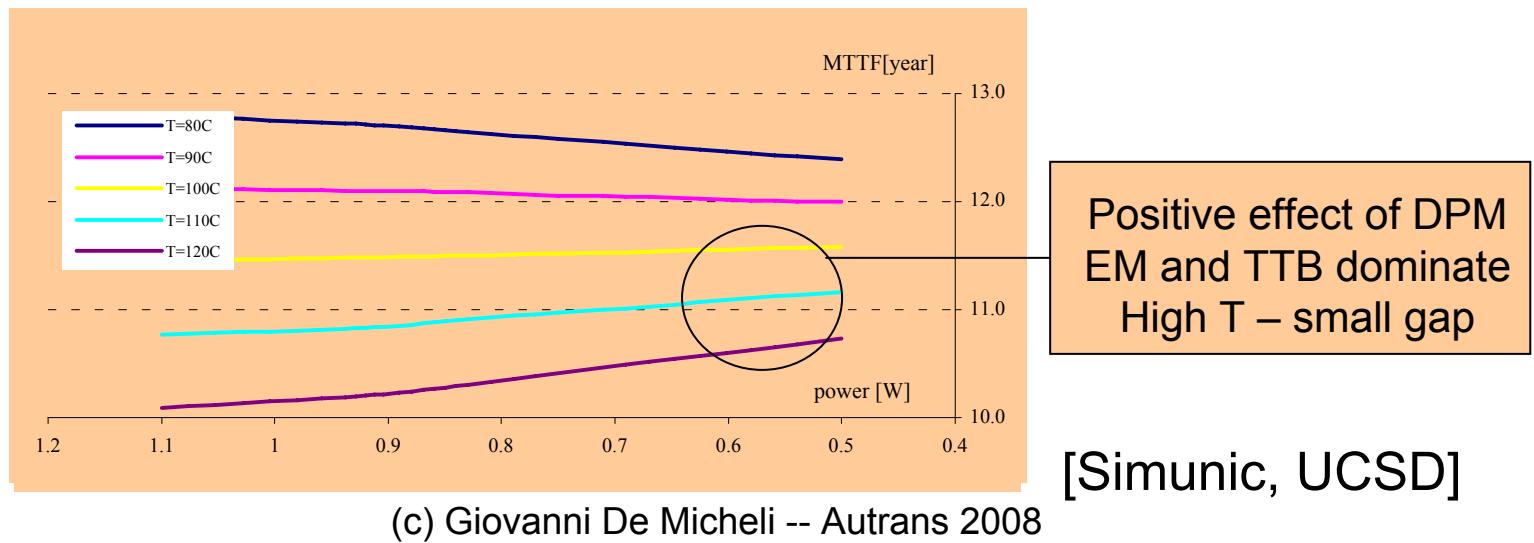
Thermal map: multiprocessor



- Temperature gradients:
 - Time-varying because of DPM/DFS/DVS
- (c) Giovanni De Micheli -- Autrans 2008

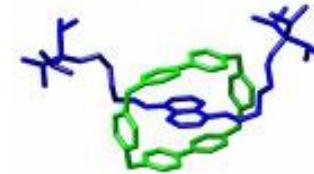
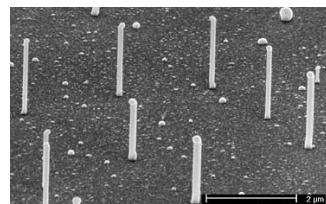
Thermal management

- Keep chip as cool as possible
 - Reduce failure rates and power consumption
- In multi processor (core) system,
power management shuts down idle cores
 - The temperature distribution will change in time
 - Thermal stress may increase
- Balance temperature reduction and thermal stress

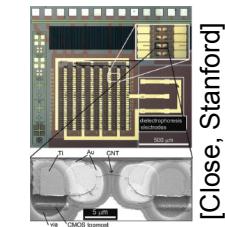
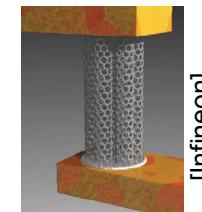
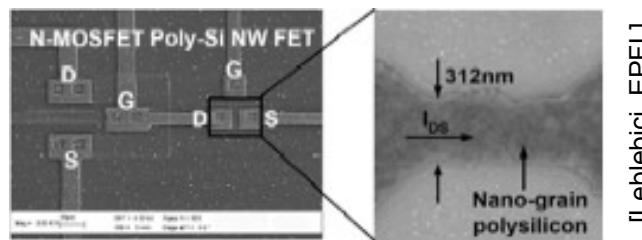


The fabrication technology support

- Beyond CMOS: a myriad of new ideas



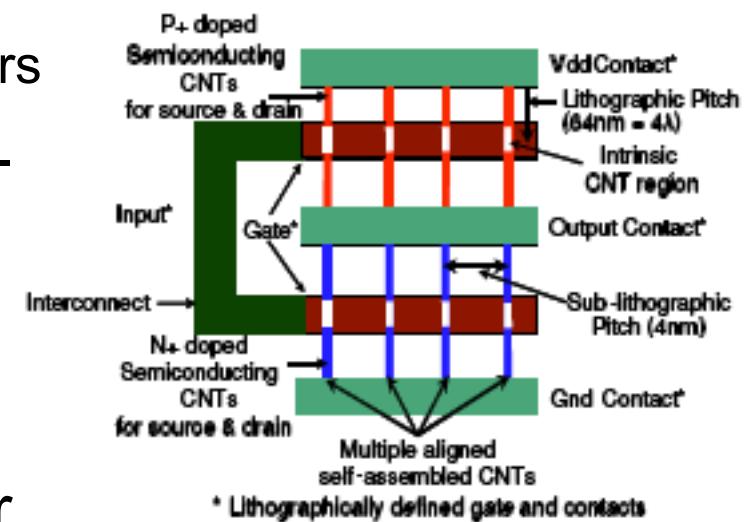
- Are these technologies apt/ready for system design?
- Can they mix and match with CMOS?



- How do we design with these technologies?
 - Higher defect densities and failure rates

Enhancing silicon technology

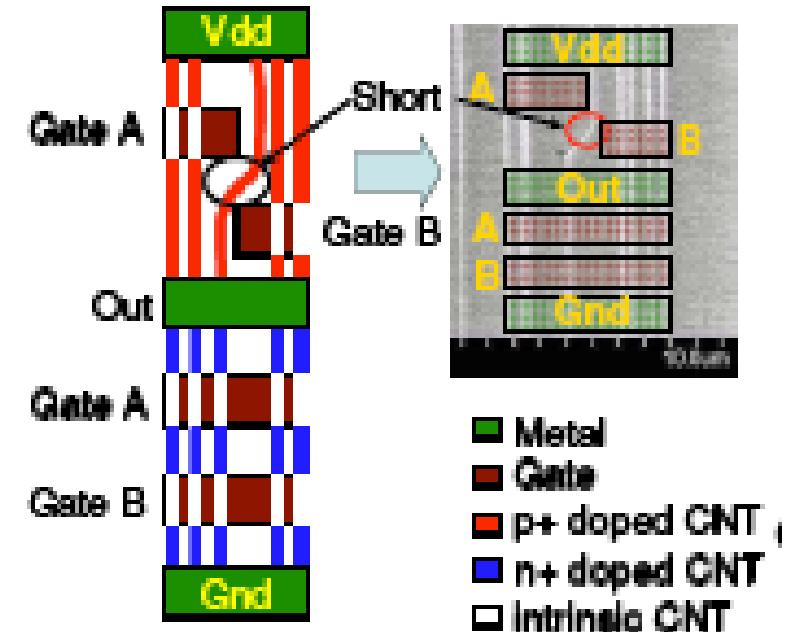
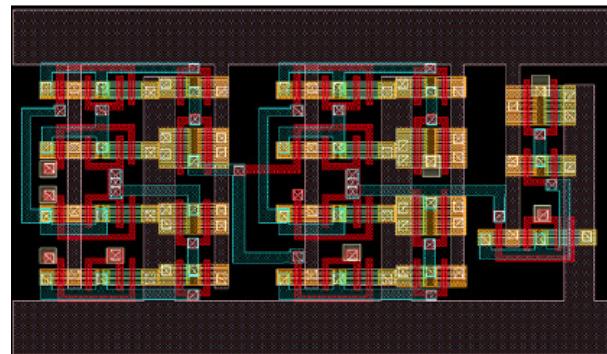
- CMOS-like process
 - CNT wires deposited on Si wafers
- CNT transistors within CMOS-style layout
 - Higher speed
 - Smaller size
- Physical design must allow for CNT misalignment



[Mitra - Stanford 07]

Design issues

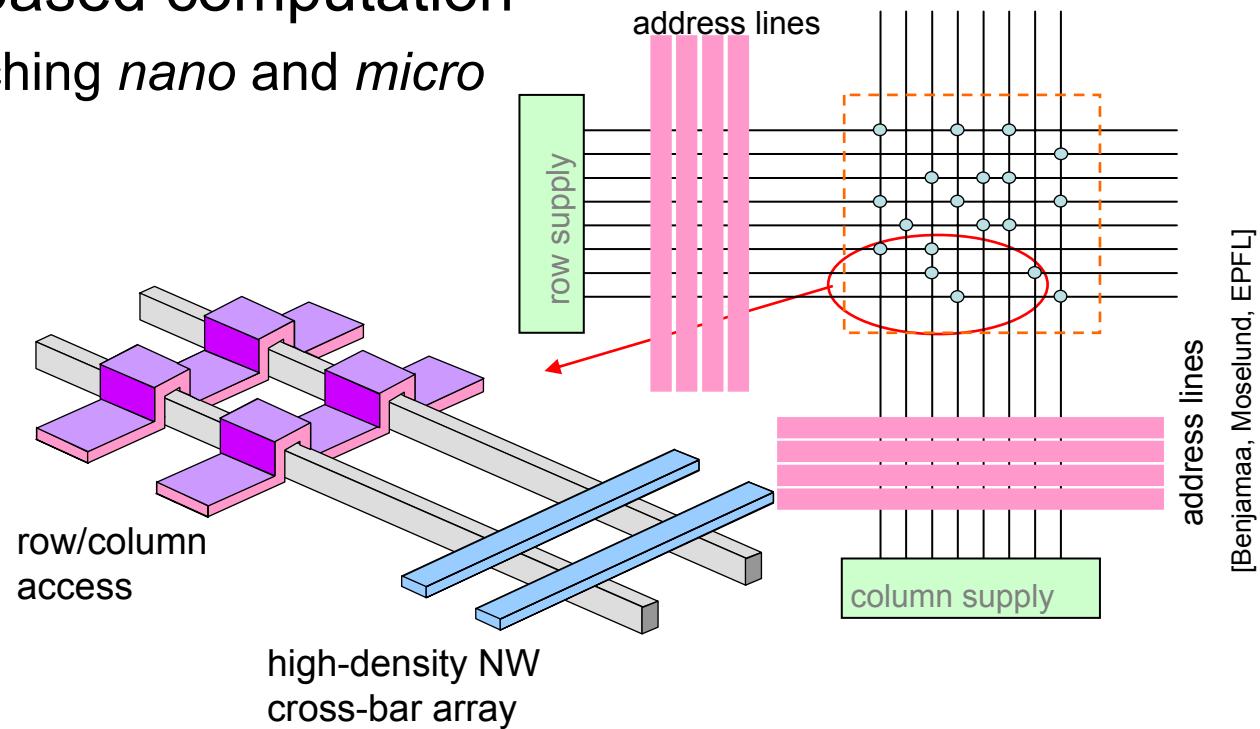
- CNT wires directions are statistically distributed
- A misaligned CNT can create a logic malfunction
- Specific design and etching steps can insure correct operation



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New computational structures

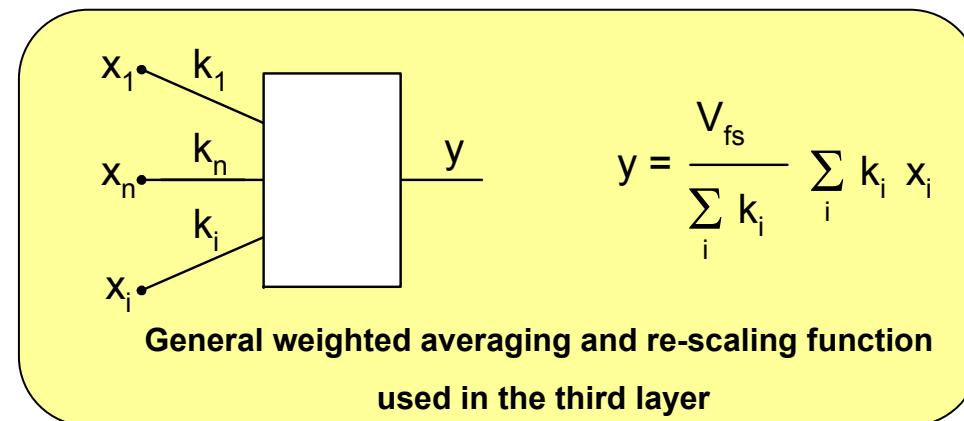
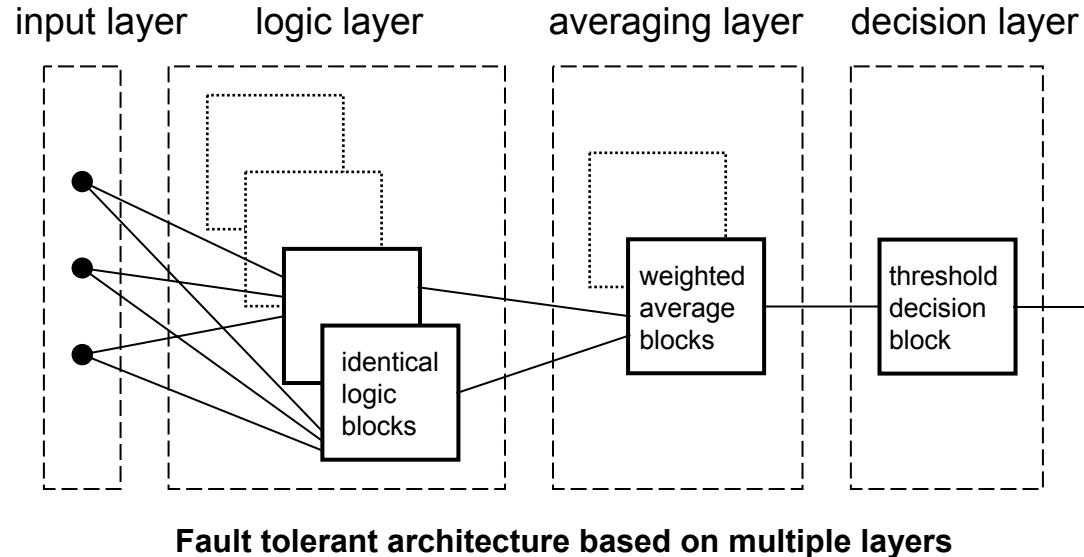
- Computation requirements
 - Predictable design
 - Fast design closure
- Array based computation
 - Matching *nano* and *micro*



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Reliable nano-design

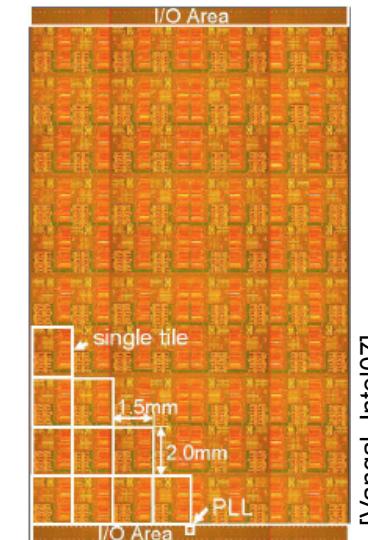
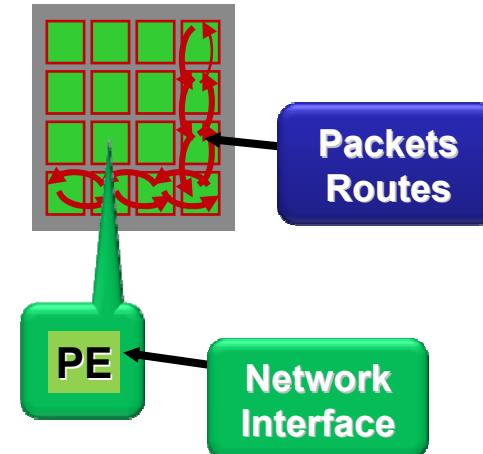
Weighted averaging



[Source: Leblebici and Schmid]
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New communication structures

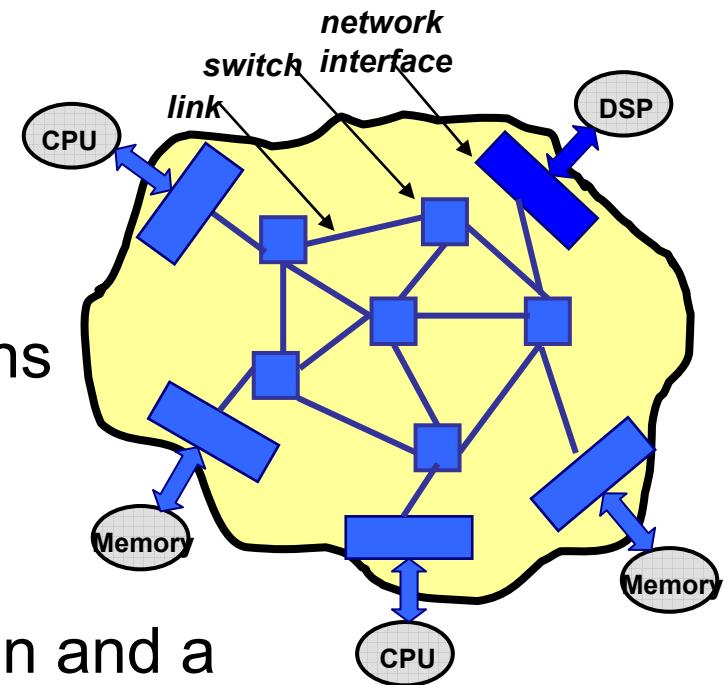
- Design requirements:
 - Predictable design
 - Fast design closure
- Network on Chip communication
 - Modular and flexible interconnect
 - Reliable on-chip communication
 - Structured design with synthesis and optimization support



[Vangal, Intel07]

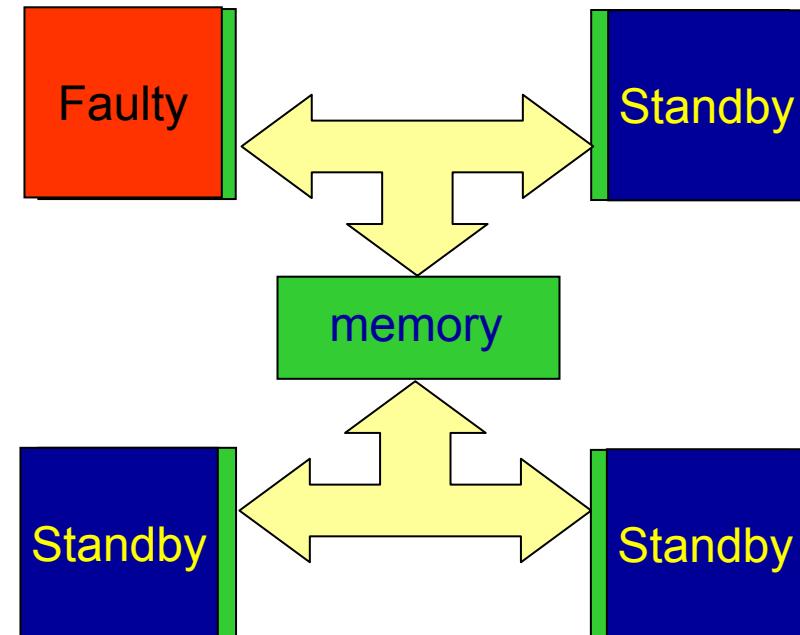
Flexibility in NoC design

- NoCs have modular structure
 - Core interfaces
 - Switches/routers
 - High-speed links
- NoCs can be tailored to applications
 - Topology selection
 - Switch/link sizing
 - Protocols
- Several parameters for optimization and a large design space
 - NoC synthesis and optimization



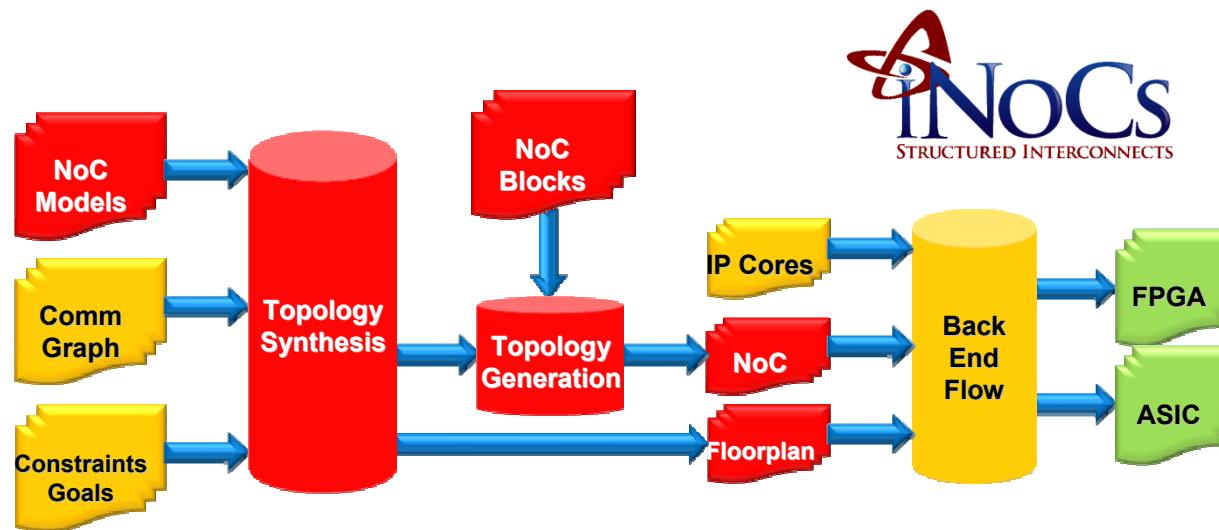
Reliability with NoC design

- Error detection/correction at various levels
 - Small electric swings allowed: electrical / physical imperfections corrected at the logic levels
 - SoCs can scale-up in size and performance
- Multi-path links provide redundancy of the interconnect structure
 - Alternative paths
 - Graceful degradation
- NoCs support seamlessly component redundancy
 - Insertion of stand-by components
 - Removal of failed components
 - Load sharing

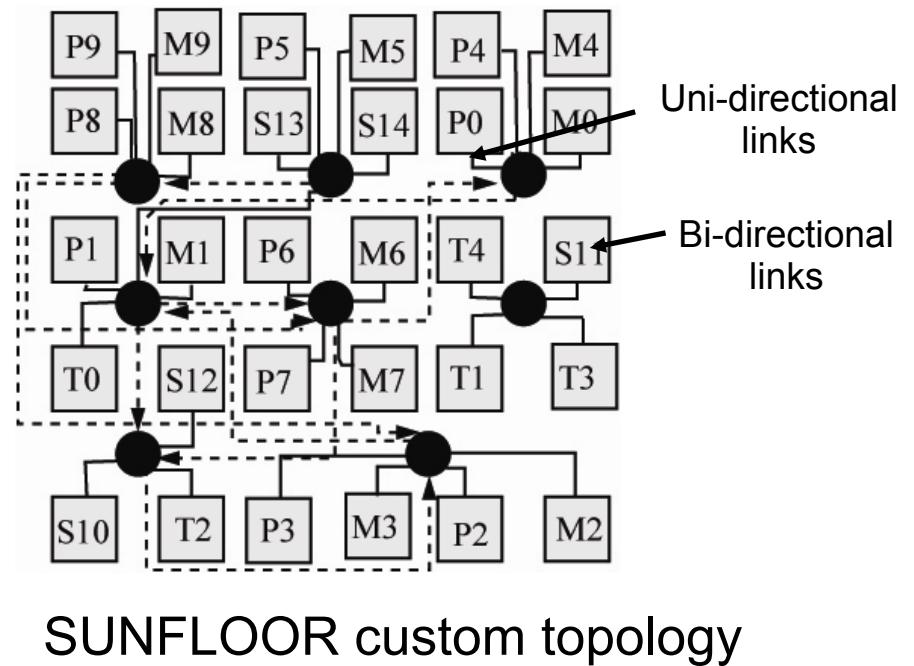
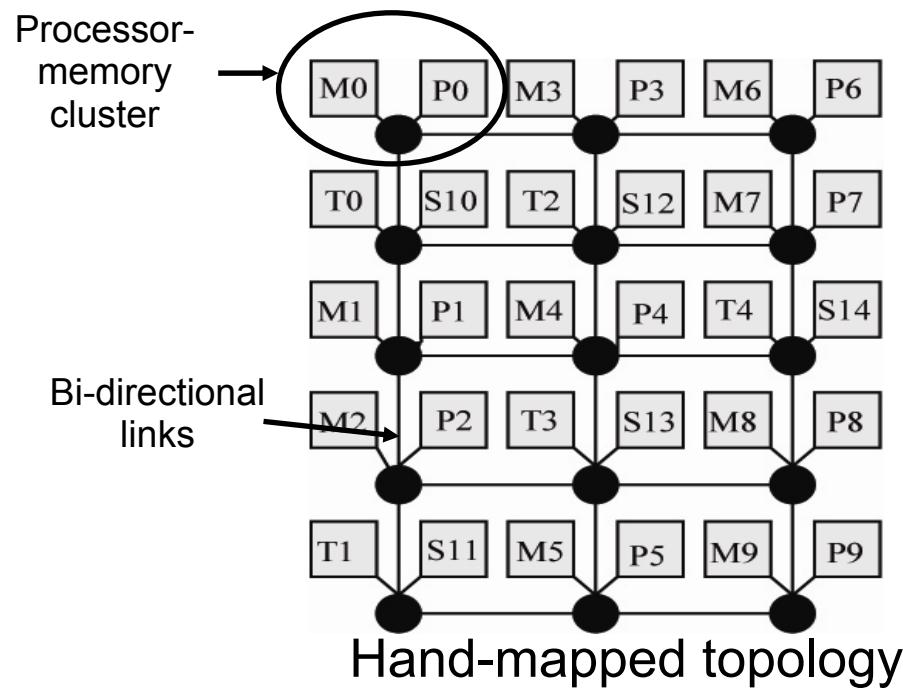


Synthesis and optimization for NoCs

- Full tool flows for NoC Design
 - Raising the paradigm of physical design
 - From topology selection to component-level synthesis
- Synthesis and optimization at various levels



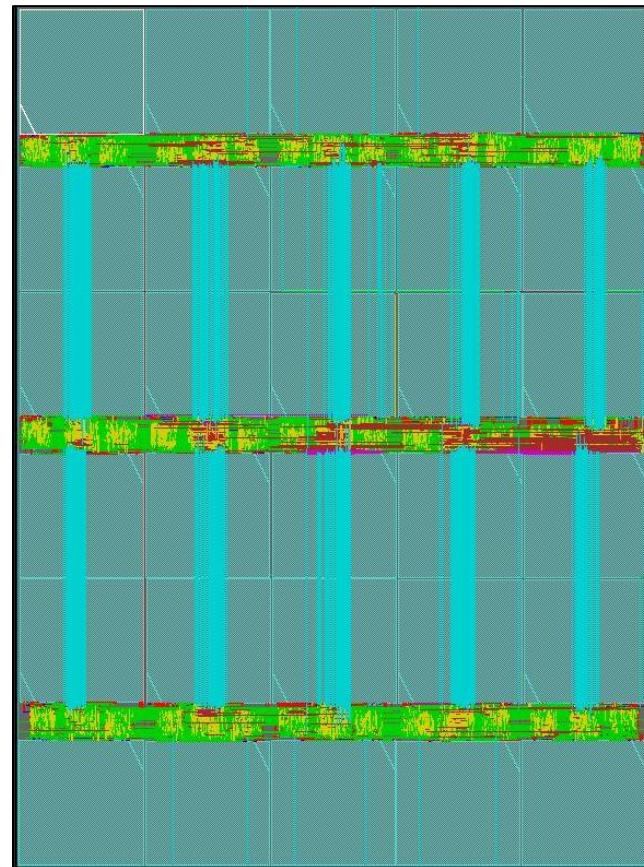
SUNFLOOR vs. manual design multimedia chip with 30 cores



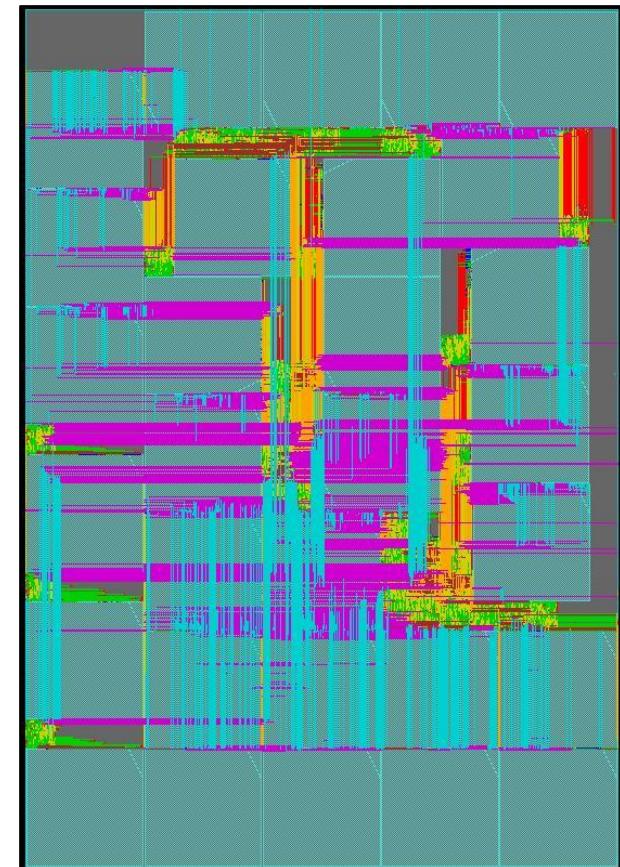
P-processors, M-private memories,
T-traffic generators, S-shared slaves

Design layouts

From Cadence
SoC Encounter



Hand-design (custom mesh)



SUNFLOOR Design

SUNFLOOR vs manual design

Manual design:	SunFloor:
<ul style="list-style-type: none">Topology: 5x3 mesh (15 switches)	<ul style="list-style-type: none">Topology: custom (8 switches)
<ul style="list-style-type: none">Operating frequency: 885 MHz (post-layout)	<ul style="list-style-type: none">Operating frequency: 885 MHz (post-layout)
<ul style="list-style-type: none">Power consumption: 368 mW	<ul style="list-style-type: none">Power consumption: 277 mW (-25%)
<ul style="list-style-type: none">Floorplan area: 35.4 mm²	<ul style="list-style-type: none">Cell area: 37 mm² (+4%)
<ul style="list-style-type: none">Design time: weeks	<ul style="list-style-type: none">Design time: 4 hours design to layout
<ul style="list-style-type: none">0.13 μm technology	<ul style="list-style-type: none">0.13 μm technology

constraint

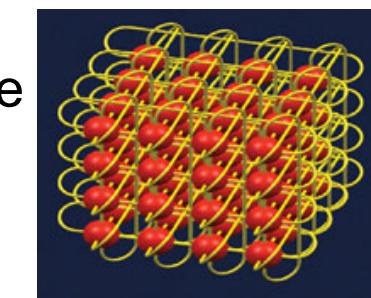
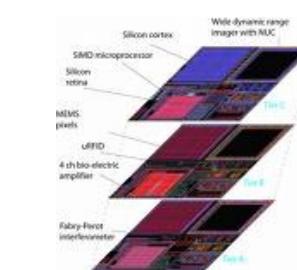
Benchmark execution time comply with application requirements and are even 10% better on SunFloor topology

New packaging technology

- From planar to 3D integration
 - Chips have limited wiring resources
 - Electrical and manufacturing constraints limit heterogeneous planar integration
- *Through silicon vias* allow designer to stack:
 - Computing arrays
 - Memory arrays
 - Analog and RF circuitry
- 3D NoCs provide effective and reconfigurable means of realizing communication



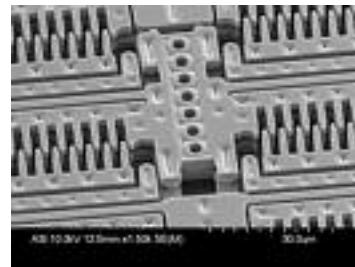
[Fraunhofer]



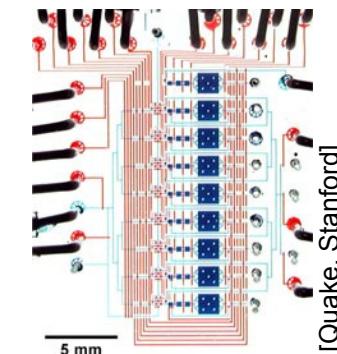
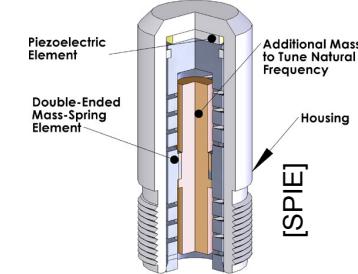
[IBM]

Heterogeneous integration

- Electrical and mechanical parts
 - Microactuators, scavengers, microfluidics

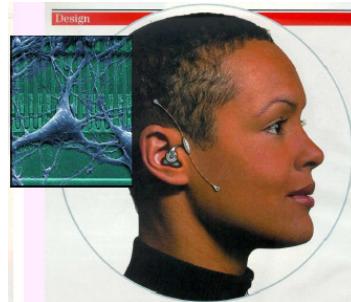


[Sandia]

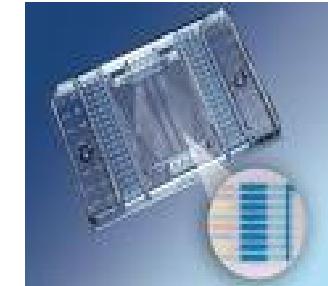


[Quake, Stanford]

- Electronics meets the living world



[Un. Missouri]



[RSC]

- Universal co-design

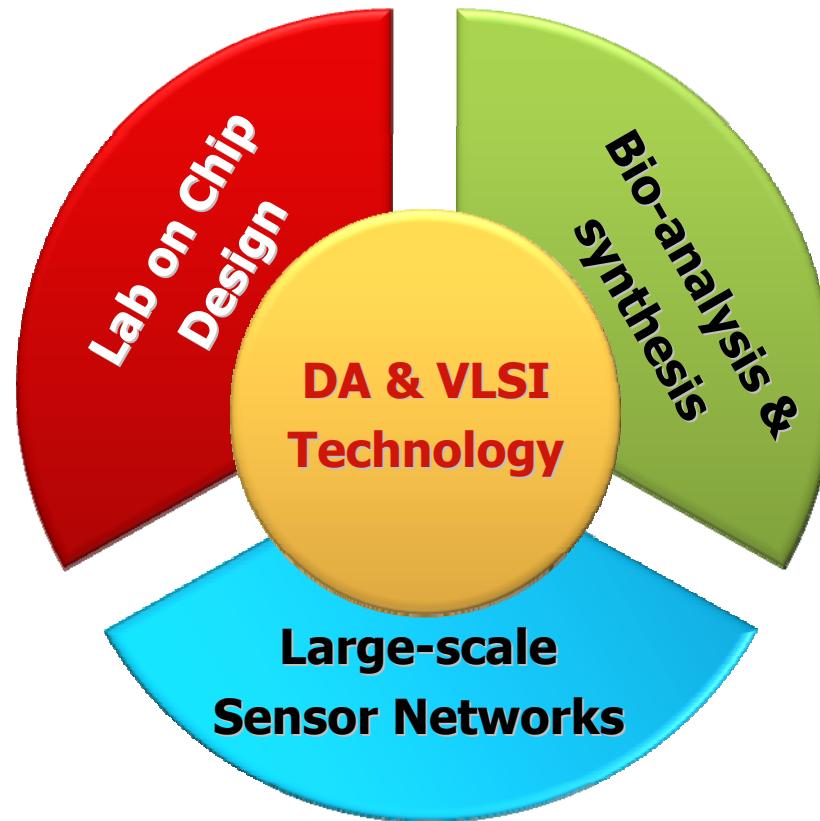


SYSTEM FAILURE

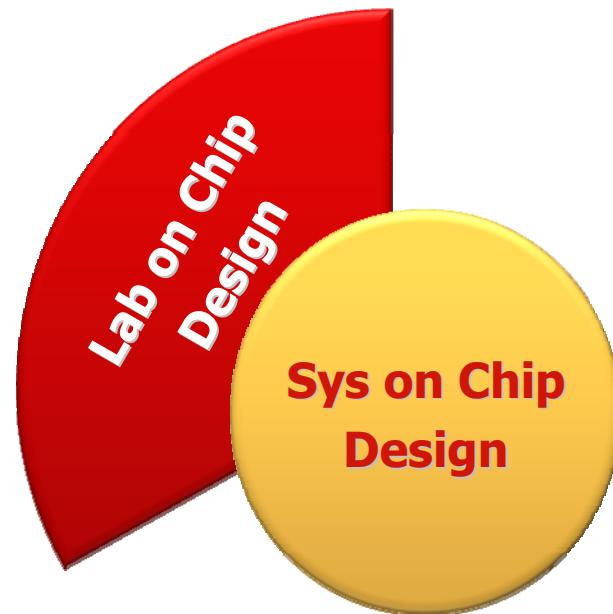
The enabling design technology

- System-level design technology
 - Evolution of EDA
- Modeling, analysis, synthesis
 - The discipline brought by EDA enabled very complex chips to be successfully designed and operated
- A bigger perspective
 - How to engineer complex multivariate systems
 - Address all aspects of embedded system design
- Scientific and commercial value stems from the systems aspect

DA evolution through three illustrative examples



Lab on Chip design



Computer-aided diagnosis (CAD?)

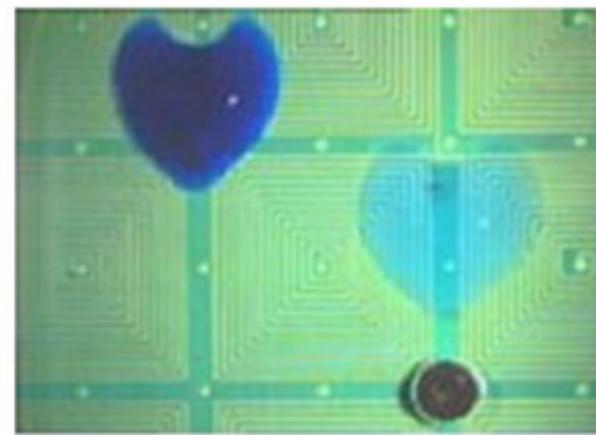
- *Lab on chip* at point of care
 - Perform biochemical test on the field
 - Faster, cheaper, more effective...
- How
 - The ultimate hybridization of technologies:
 - Microfluidic: sample transport
 - Sensors: binding proteins, DNA to probes
 - Low-noise electronics
 - Powerful data processing algorithms and software
- A promise of lab on chip is to revolutionize medical care and offer personalized medicine



(c) Giovanni De Micheli -- Au



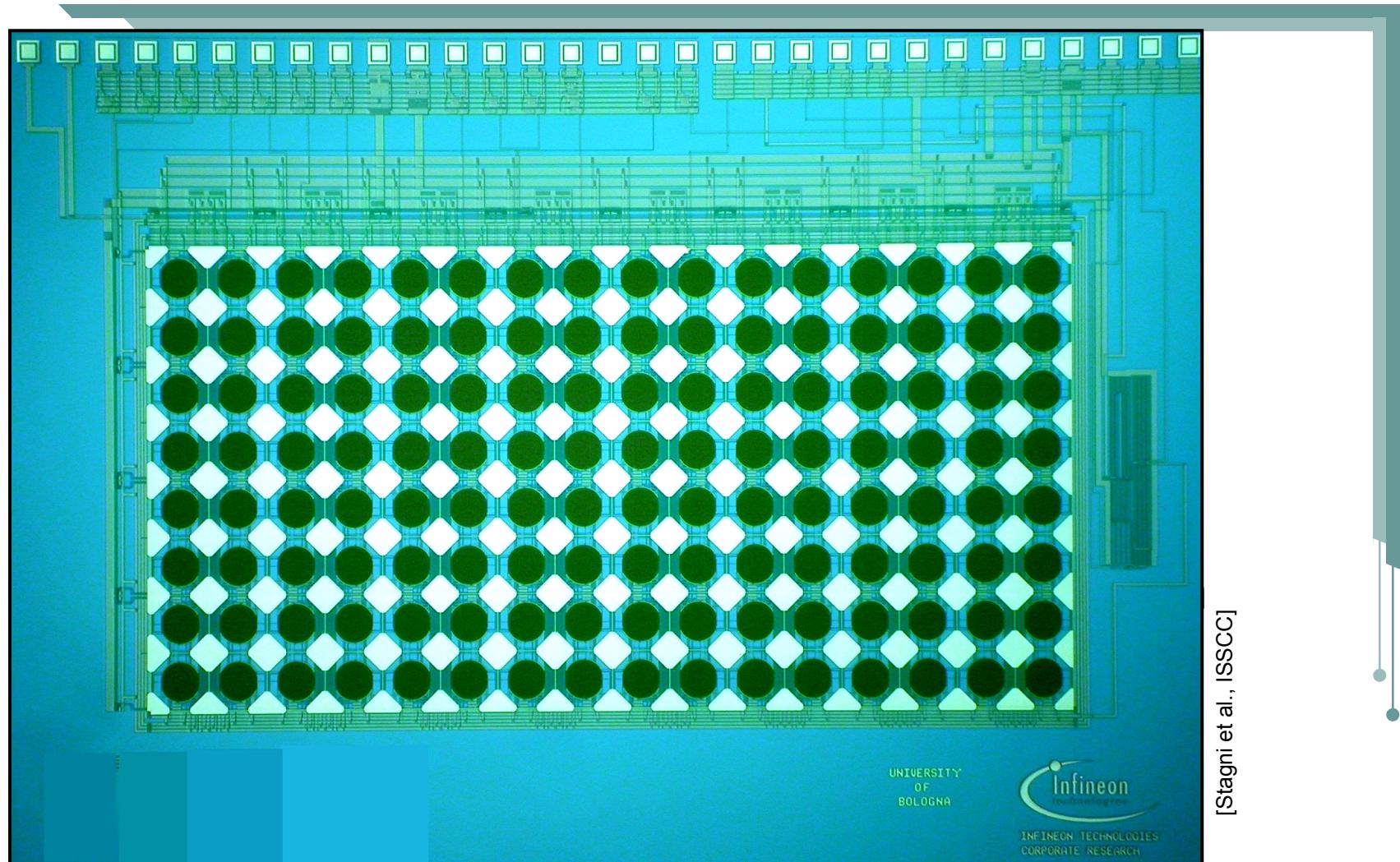
Sample transport



[Gjls, EPFL]

- Cell or sample transport, split and merge
 - On a 2-dimensional array
- Parallel scheduling and routing of multiple samples

Sensing



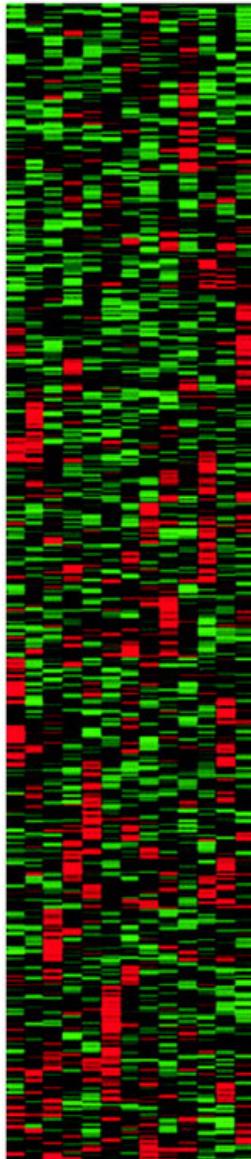
- Array detectors yield a matrix of expression levels

Data mining and interpretation

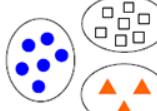


(c) Giovanni De Micheli -- Autrans 2008

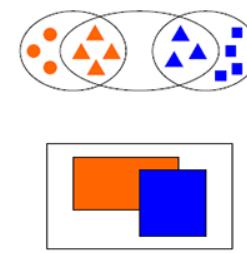
Data interpretation and clustering



) Giovanni De Micheli -- Autrans 2008

- Grouping similar objects together
 - Detecting gene variations consistent with the sample choice
 - Inference of specific conditions
 - Bi-clustering on large data sets
 - Simultaneous cluster of subsets of rows and columns
 - Gene and samples
- 

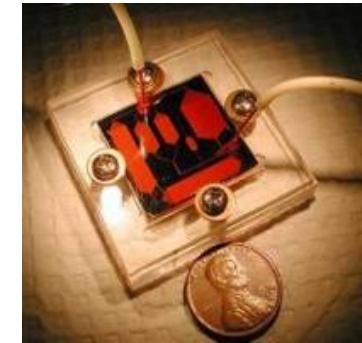
(a) Clustering



(b) Biclustering
- Problem solved with ZDD technology
 - Fast and complete data interpretation

Global *Lab on Chip* objectives

- Bio-discovery
 - New biological mechanisms
- Medical practice
 - Better diagnosis via genetic information
 - Linking genetic data to clinical traits and databases
- Micro-chemistry
 - Creating organic compounds by micro-reactions
- Support for experiments/tests on the field
 - Generic versus application-specific *lab on chips*
 - Programmable, field-programmable?



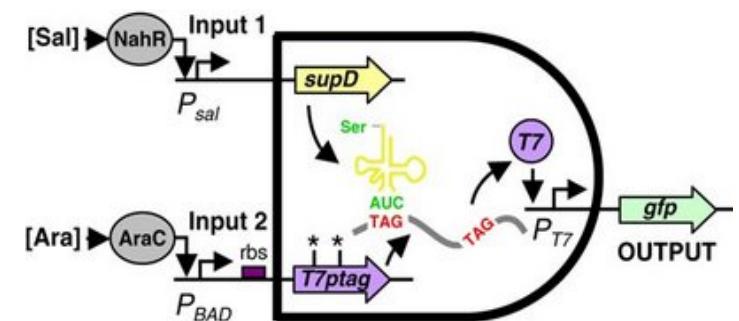
[Schuler,Cornell]

Bio analysis and synthesis



Analysis and synthesis

- Analysis - understand biological mechanisms
 - Comprehend in full the value of the *omics*
 - Genomics, proteinomics, transcriptomics
- Synthesis - modify/create new realities
 - Synthesize drugs that alter genetic/metabolic pathways
 - Pharmacogenomics
 - Synthesize biological compounds that support computation
 - Synthetic biology
- Multiple abstractions are needed for analysis and synthesis



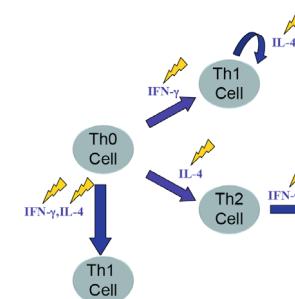
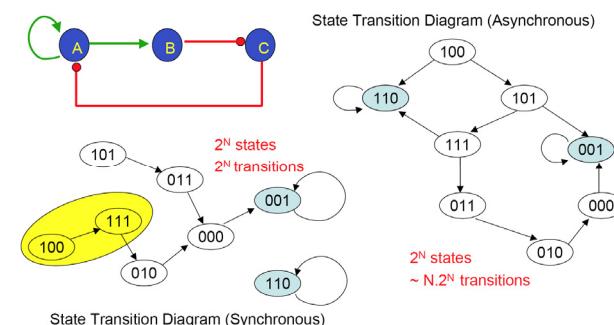
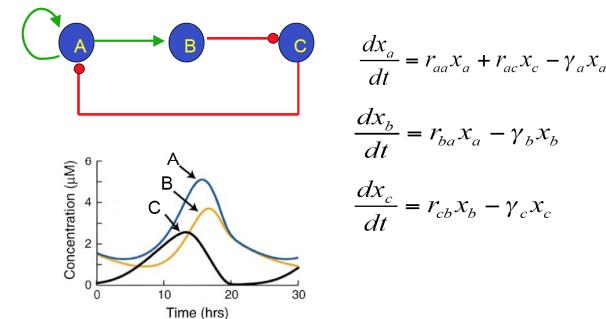
[UCSF,UCB]

Abstractions

- Bio-chemical abstraction
 - Event timing
 - Differential equation models

- Logic level abstraction
 - Zero-delay model
 - Finite-state system
 - Synchronous, asynchronous

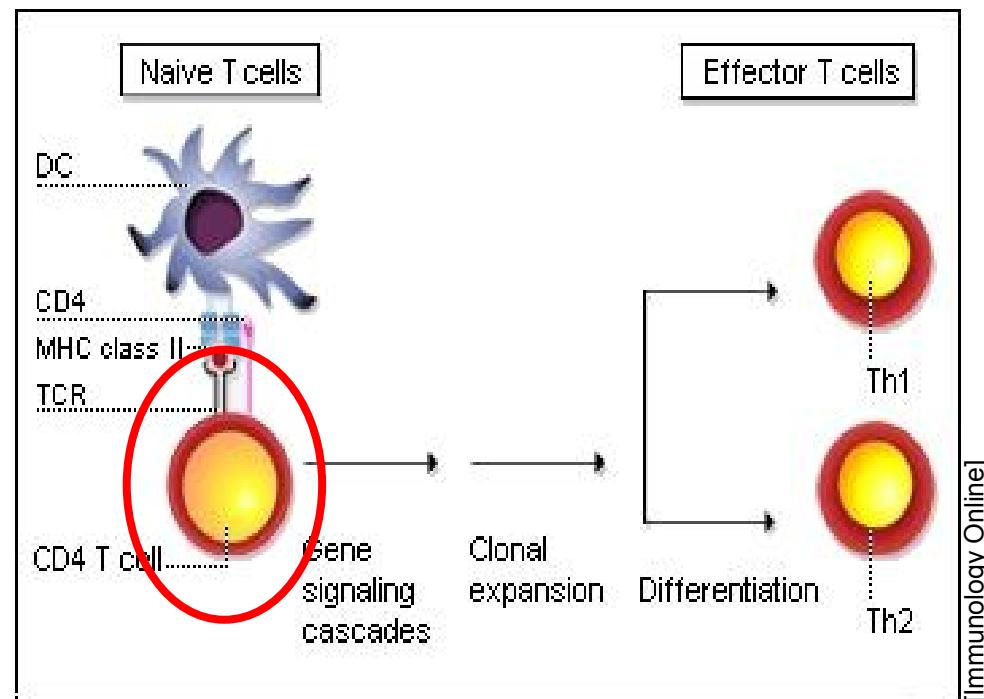
- Functional abstraction
 - Biological function
 - Input-output analysis



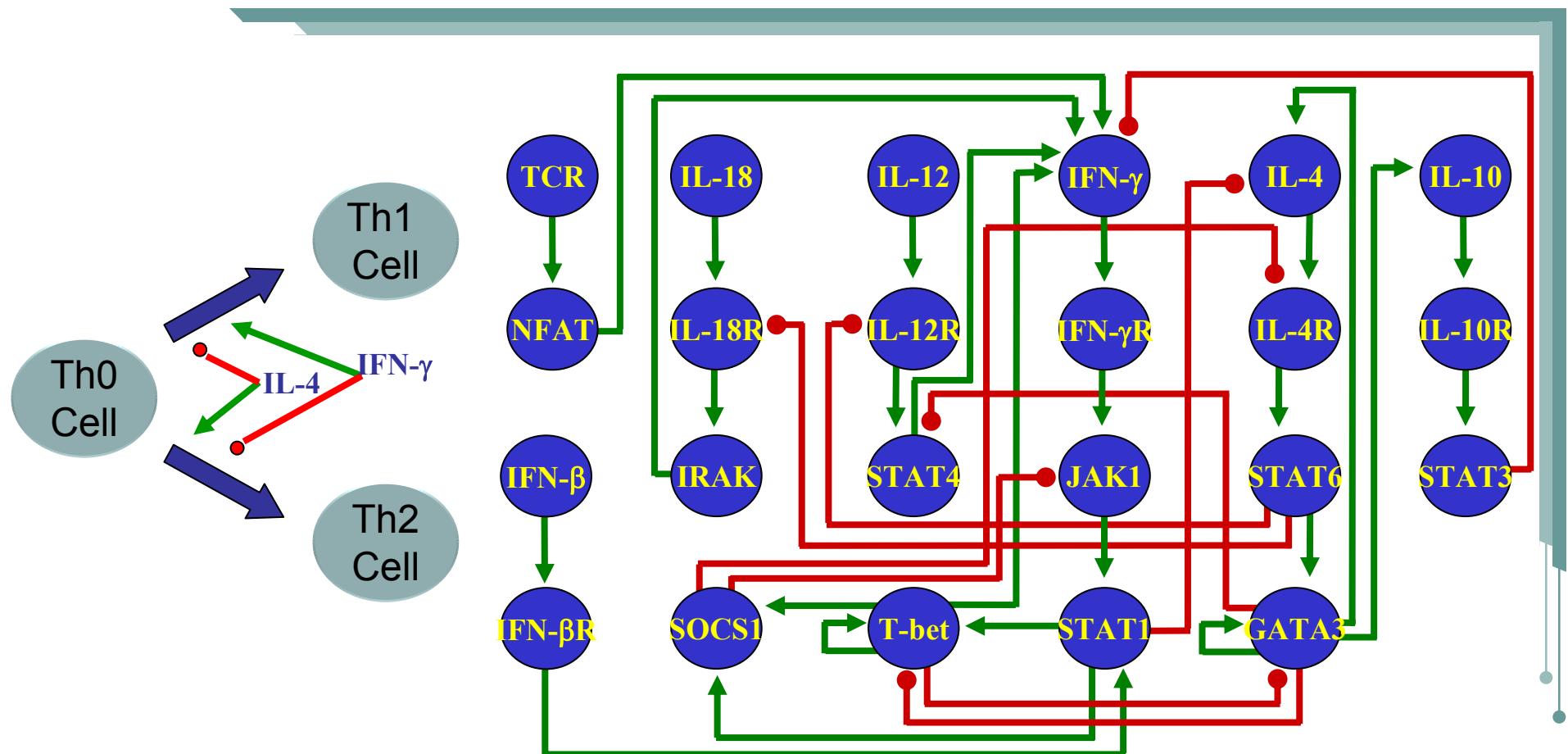
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T-helper cells

- Observed behavior:
 - Precursor Th0 cells yield:
 - Effector Th1 cells
 - Effector Th2 cells
- Evolution depends on specific gene expressions
- Evolution can be captured by a *gene regulatory network*



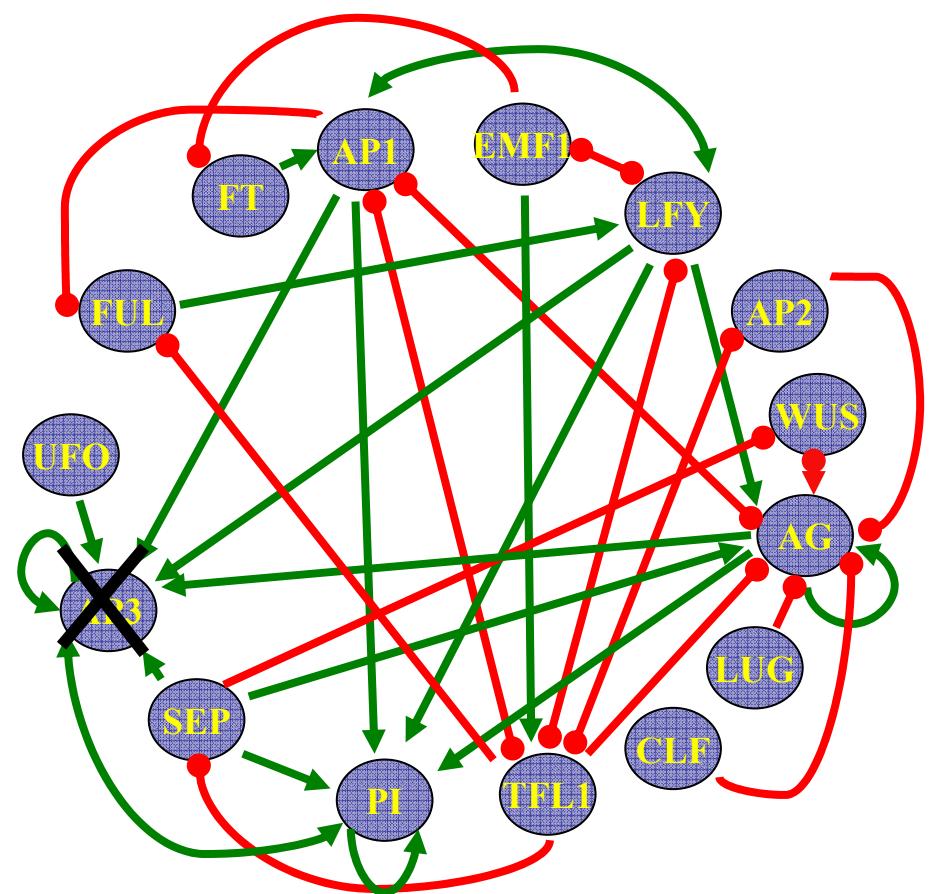
Functional and logic-level model of T-helper cell



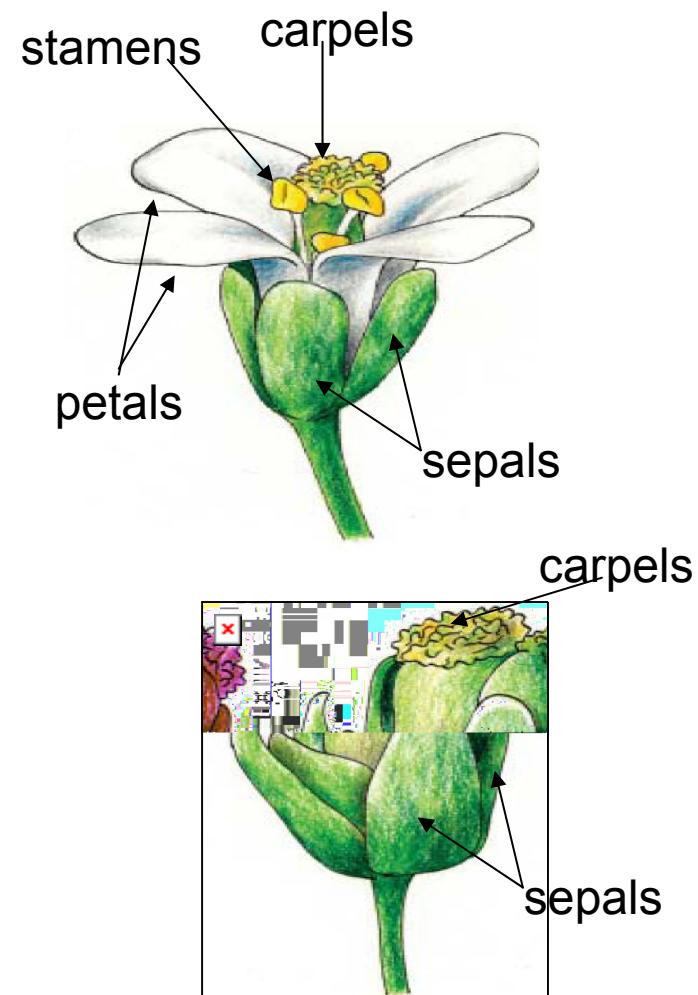
Issues

- Orthogonalization of concerns
 - Focus on terminal behavior independent from timing
- Simulation versus traversal
 - Steady state is often the objective
 - Implicit methods can handle large amount of data
- Modify system by perturbation
 - Knock-out experiment *in silico*
 - Silence a gene
 - Stuck-at 0 (déjà vu?)

Knock-out example: *Arabidopsis Thaliana*



[Soto et al. *Plant Cell*, (16):2004]

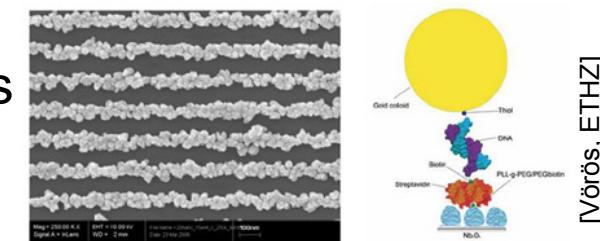


AP3 knockout

(c) Giovanni De Micheli -- Autrans 2008

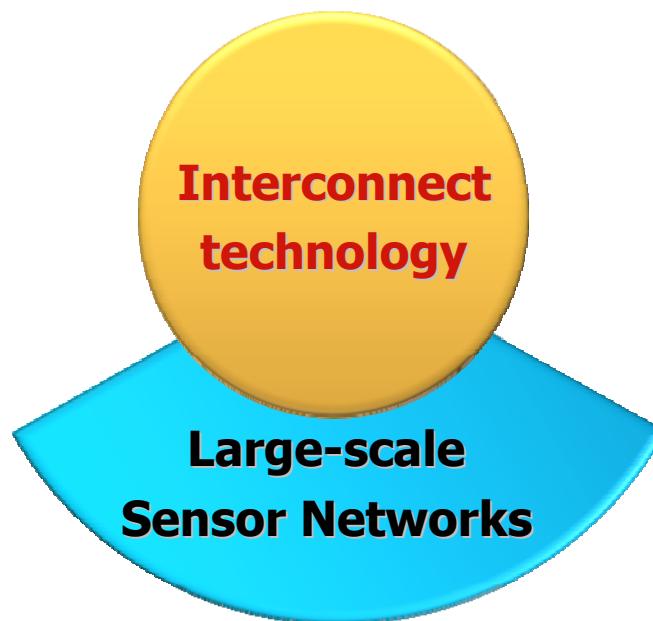
Bio analysis and synthesis objectives

- Pharmacogenomics
 - Develop drug therapy, cognizant of patient genotype
 - Study effects of altering genetic/metabolic pathways
- Synthetic biology
 - Engineer systems based on biological components
 - Abstraction: libraries, synthesis process
- Biology-driven computation
 - Devise computational processes performed by DNA
- Biologic scaffolding
 - Construct nano structures/circuits using DNA composition



[Vörös, ETHZ]

Environmental monitoring and control



The environment

- We are embedded in the environment
 - Many inconvenient truths



- What are the challenges of wireless sensor networks to monitor/control the environment ?
 - Massive amount of data to process
 - Distributing and powering the nodes
 - Providing redundancy to tolerate local failures

Engineering environmental systems

- Integrated sensing, computation, communication and embedded software
 - Local vs. global data processing and communication
- The power of data abstraction
 - Data reduction and integration
- The distributed intelligence approach
 - Reason and act locally with (some) global information
 - New computational paradigms,
as compared to classical supercomputer approaches



[Thiele, ETHZ]



The quest for energy efficiency

- Distributed wireless systems must (eventually) be autonomous
 - Energy harvesting from the environment
 - Mobile and fixed applications
 - Convert unused (degraded) energy into information

- Energy distribution systems must be efficient
 - Use information on the system to optimize energy distribution
 - Smart home, building, factory, ...
 - Electric grid management
 - Convert information into energy savings

- Mutual interaction: **energy ↔ information**
 - Policies for run-time energy/information management will play a key role in system design



[Perpetuum]



[Sandia]

How do we interact with the environment?

[Summer School 2058@172.165....]



[Masternewmedia]

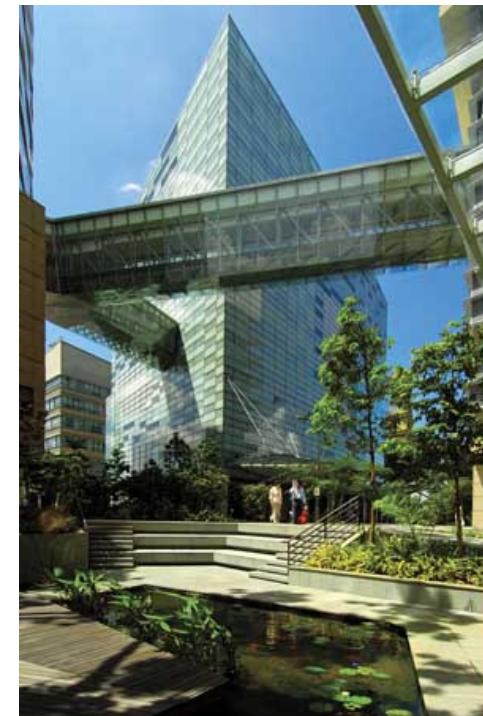
- How to design evolvable embedded environments with user interaction and immersion?

Cooperative engineering

- Bringing together engineer/scientists/doctors with different skills
 - Communication and vocabulary
 - Abstraction and modularity
- Collaborative workspaces

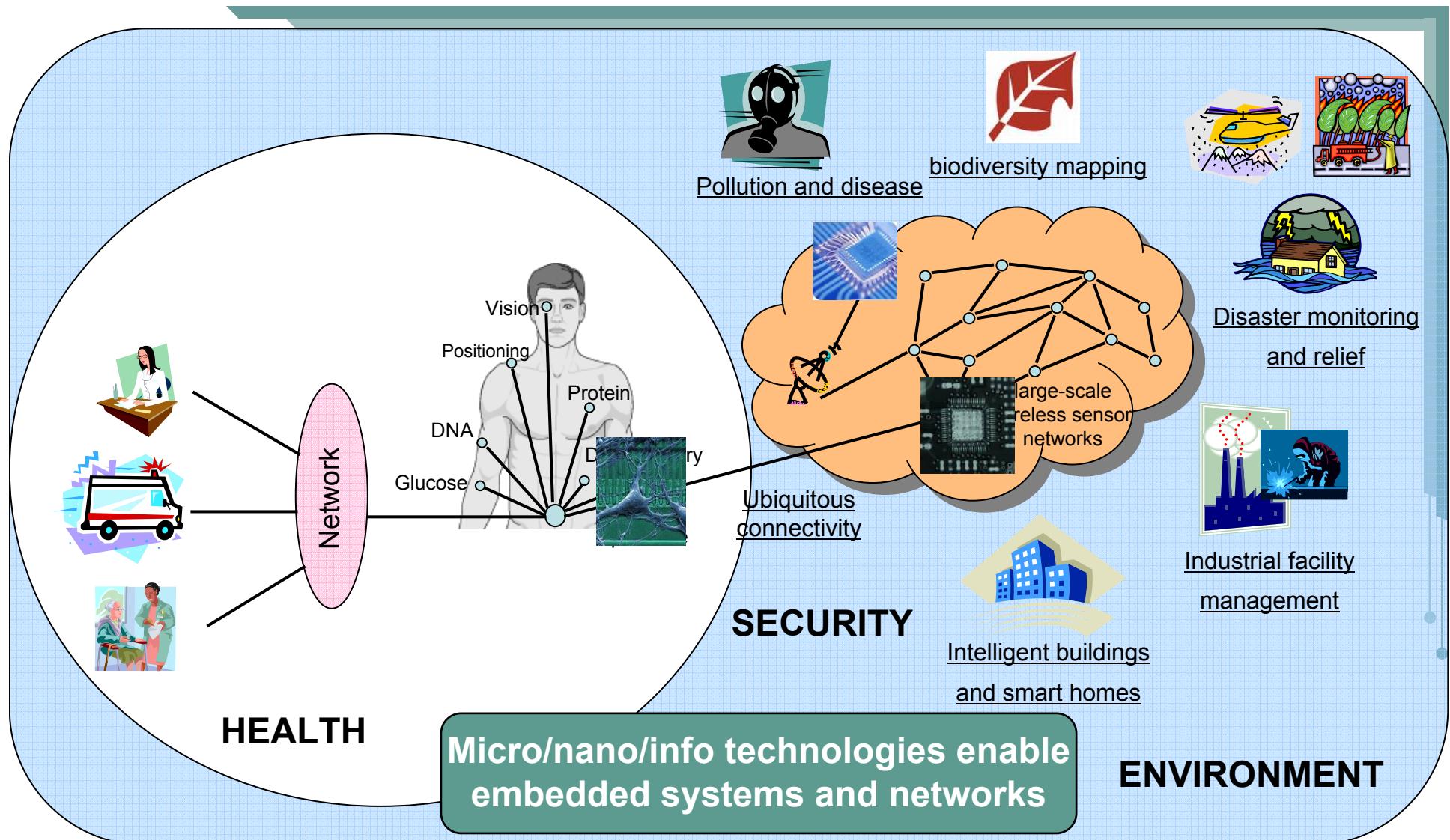


[Stanford Clark Center]

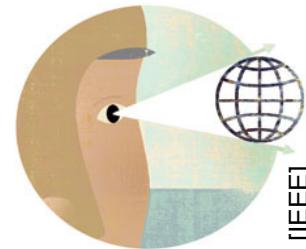


[Singapore Biopolis]

The nano-tera.ch program



The humanitarian technology challenge



- A new partnership between the IEEE and the UN
- Identify technologies in the health/environment domain that can benefit developing countries
 - Food, water, health monitoring
- Using cellular technology to link data
 - Ubiquitous connectivity and local data processing
 - Autonomous or very low-power consumption because of limited availability of energy
- An ethical objective that can raise enthusiasm among engineers

Summary

- The road ahead has challenges and rewards:
 - Expanding our horizon is key to scientific viability and commercial profitability
- We need heterogeneous hardware design and the corresponding software infrastructure
 - Product/system design is an extremely complex task, because of the variety of facets and technologies involved
- System-level design technologies are crucial for system conception, design and management
 - Progress leads us beyond advanced silicon chip design
 - Scientific and financial benefits will stem from the system/service perspective



Thank you

